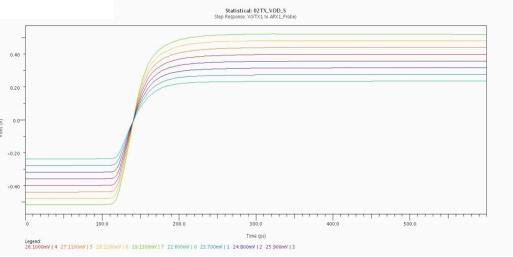


# IBIS AMI VALIDATION IBIS SUMMIT DESIGNCON 2014





Santa Clara, CA, January 31, 2014 Zilwan Mahmod, Anders Ekholm

### AGENDA



- Design goals
- > IBIS AMI Validation
  - IBIS AMI Certification
  - PCB Passive correlation
  - TX Active correlation
  - RX Active correlation
- > Experiences

### DESIGN GOALS



- > What design goal do we have with IBIS AMI analysis?
  - To verify a robust design over manufacturing variations.
  - To verify a given design criteria like BER, Eye mask.
  - To optimize the design eye to the given criteria.
  - To verify the design with a high fault coverage.
  - To verify the design in a short predictable timeframe.
  - To minimize design iterations.

#### IBIS AMI VALIDATION



To achieve the design goals we need correct and accurate models with high performance.

- > How do we validate IBIS AMI models?
  - IBIS Checker
  - Certification
  - Active correlation
    - > TX correlation
    - > RX correlation

### IBIS AMI CERTIFICATION



Certification is the first step an IBIS AMI model needs to go through, this is to check that the model behavior is reasonable.

- Certification needs to check the following:
  - Is the model delivery complete, all files included?
  - Does this model describe enough variation, process corners?
  - Does this model describe all possible configuration parameters?
  - And only the possible configuration parameters?
  - Is it compliant with the IBIS AMI standard (IBIS 6.0 specification)?
  - Is it compliant with Ericsson requirements outside of IBIS AMI standard?
  - Is the model describing the buffer's electrical behavior accurately?

### IBIS AMI CERTIFICATION



- > Certification needs to check the following cont.:
  - Is it compatible with the used simulation environment?
  - Are the necessary jitter parameters included (for both TX and RX)?
  - Is documentation complete enough to use the model?
  - Is the model performance fast enough?
  - Are the configuration parameters the same as the real IC uses?
  - If not are there information on how to translate parameters from the model to the physical IC settings?
  - Are the settings reasonable and in correct order?
  - If model is interoperable with other vendors models?
- Output is a certification report

### PCB PASSIVE VALIDATION



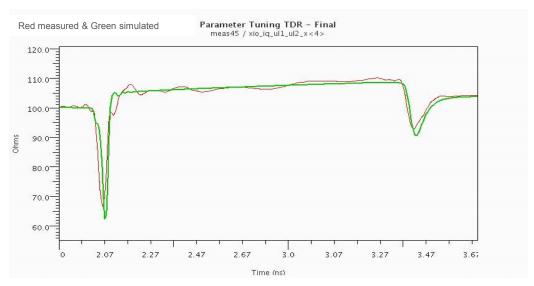
To be able to do active correlation we need to make sure our simulation environment are predicting our passive interconnect accurately enough.

- >We achieve this by doing passive correlation, or simulator calibration (similar to measurement instrument calibration).
  - Produce a PCB using the material and stackup selected for the design.

Use TDR or VNA measurements to get a representation of the used trace

structures in you design.

- Adjust PCB Physical Parameters
- propagation delay error adjust ε<sub>r</sub>
- impedance error adjust cross-section
- attenuation error adjust tan δ, roughness

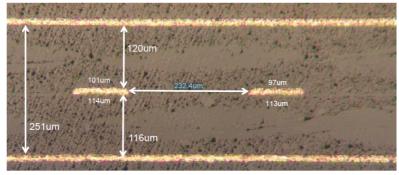


### PCB PASSIVE VALIDATION

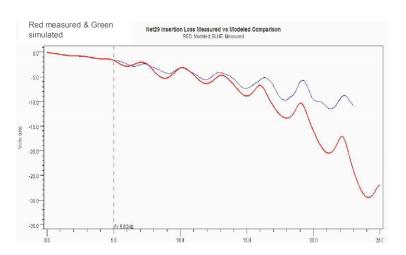


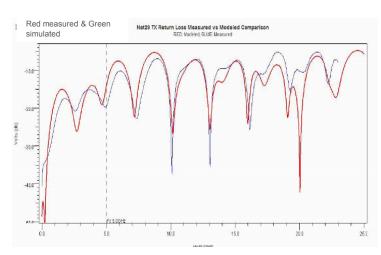
Perform cross section cuts of all relevant structures in the PCB to get

physical properties of geometries in the used simulation tool.



- Create the same data set in your simulation environment.
- Adjust/tweak the simulation model parameters to achieve an accurate enough result. So the passive model will predict your system performance.





### TX ACTIVE VALIDATION MEASUREMENT ENVIRONMENT

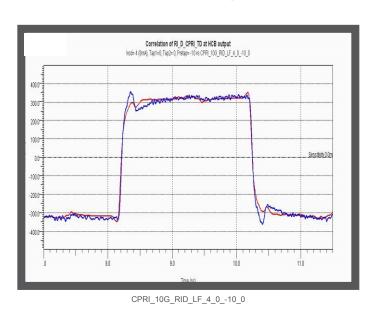


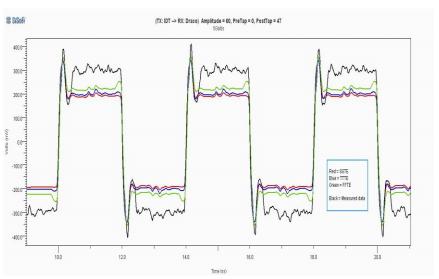
- > Select suitable trace loads for correlation.
- > Run a set of cases of IC configuration settings.
  - Run a slow clock from TX and measure waveforms.
  - Run a PRBS (eg. PRBS7) and measure waveforms.
  - Transfer waveform data to simulation environment.
- > "deembed" measurement or "embed" simulation.
- Make sure to use the same measurement point.

## TX ACTIVE VALIDATION SIMULATION ENVIRONMENT



- > Simulate the same traces with the same probe point
- > Simulate for the same stimuli cases
- > Make an overlay correlation of the waveforms





### RX ACTIVE VALIDATION



RX correlation methods is still being determined.

- -How can we correlate at Decision Point?
- -Standard waveform overlay correlation will not be possible.
- -Maybe a Feature Selective Validation (FSV) is possible?
- -Which Features should be Selected for correlation?

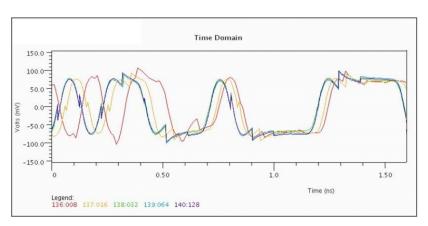
IC internal meas. features are not standardized. 🕾

- -Makes the FSV correlation harder.
- -Can IBIS Open Forum standardize this?



#### Many models fails during certification

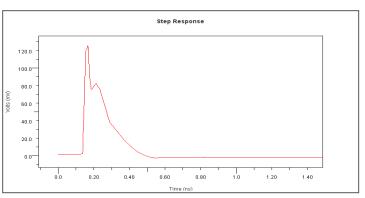
- -A.AMI controls incomplete
  - >H/W has more settings than AMI model.
  - AMI model has more settings than H/W.
  - >AMI file has fixed values for all settings.
  - Misses dependency tables.
- -Algorithmic models don't run
  - >Compiled for wrong O/S.
  - External runtime libraries required.
- -Model controls don't work
  - Changing settings has no effect.



Changing samples/bit affects results



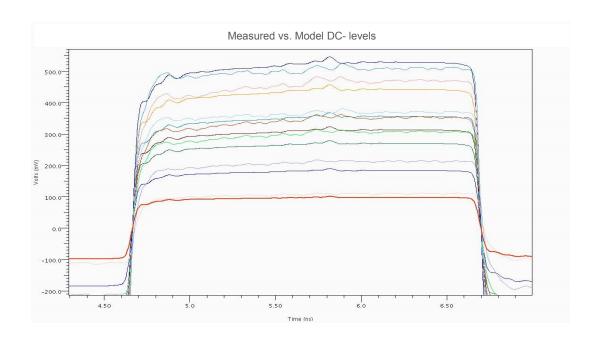
- -Models don't meet spec requirements
  - Models crash with some samples/bit settings.
- -Syntax (IBIS Parser) errors
- -Analog Models
  - Incomplete or missing data in A.ibs file.
  - Improbable analog models.
    - -Improbable voltage, impedance or behavior.
    - -"Idealized" analog models.



This is supposed to be a step response



- Some models fail during TX correlation
  - Some of the simulated DC levels don't match the measured DC levels.





- >RX correlation process is still being worked on
  - Should be considered as not trustable until proven by active correlation!



### **ERICSSON**